



TDK Innoveta Inc.

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Technical Memorandum

This memorandum summarizes the changes made to convert TDK Innoveta products to full RoHS compliance. The iQB platform is used as an example.

Component Changes for RoHS Compliance on iQB Platform

- For the iQB platform (as with other TII products), RoHS conversion of our components only involves eliminating Pb. None of the other five restricted materials were ever present in the design.
- Generally, none of the components are changed in the RoHS conversion (no silicon changes, package changes, part substitutions) – only the plating on the terminals is modified to eliminate Pb.
- There are no changes to form, fit or function of the power supply as a result of RoHS conversion.
- Plating changes are summarized in the table below:

Component Category	Terminal Plating	
	Before Conversion	After Conversion
Chip Capacitors	No changes – Already RoHS Compliant	
Tantalum Capacitors	90%/10% Sn/Pb	Gold plate
Magnetics	Cu/SnPb Solder	Cu/Ni/Sn
Ferrite Cores	No changes – Already RoHS Compliant	
Diodes/Transistors/FETs	SnPb Solder	100% matte Sn
Chip Resistors	90%/10% Sn/Pb	100% matte Sn
ICs	SnPb Solder	100% matte Sn or Ni/Pd/Au
PWB	HASL (SnPb solder)	Ni/Au
Pins	SnPb Solder	Ni/Sn

- Plating changes are allowed on a phase-in basis in order to efficiently manage the material stream.
- Products ordered to RoHS-5 requirements are built using SnPb solder paste, and are sold under the standard part number.
- Products requiring full RoHS compliance are built using Pb-free solder paste, and are sold under the standard part number with a “-R” suffix appended.

For further questions, please contact your local field engineer, or headquarters directly at support@tdkinnoveta.com.